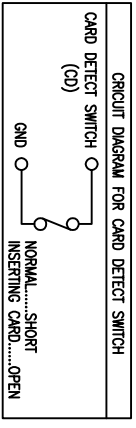


- NOTES:
- MATERIAL:
HOUSING:HI-TEMP. PLASIC UL 94V-0
CONTACT:COPPER ALLOY
SHELL:STAINLESS STEEL
 - PLATING :
TERMINAL:
CONTACT AREA: Au GOLD FLASH.
SOLDER AREA: MATTE TIN PLATED.
UNDER PLATE: NICKEL.
SHELL: NICKEL PLATED OVER ALL.
SOLDER AREA: GOLD FLASH.
 - SPECIALTY:
3.1 Rated current:1.0A
3.2 Rated voltage:30V
3.3 Contact Resistance:50mΩ MAX
3.4 Insulation Resistance:1000MΩ MIN 500V DC
3.5 Dielectric withstanding voltage: 500V AC.
3.6 Solder ability:255±5°C, 5±0.5s.
3.7 Durability:5000 Cycles Min.
3.8 Operating condition:Temperature-40°C~+85°C; Humidity 80% RH MAX

RECOMMENDED PCB LAYOUT
GENERAL TOLERANCE ±0.05

PAD
 KEEP OUT AREA



UNITS: mm		CSCONN		CSCONN PRECISE ELECTRONICS CO.,LTD	
GENERAL TOLERANCE		PART NO. (INTENDED USE)		TITLE:	
X° ±5°		CS106131413003		NANO SIM CARD PUSH 1.37H	
X.1±0.25		APPD:		DWG NO.	
X.1±2°		SK11a		SIM CARD	
X.X ±1°		DR: Kitty		SCALE	
0.XX±0.1				1:1	
				SHEET	
				1 OF 1	
				REV	
				A	